

DERAY®-Mini Shrink Device 2.0

The DERAY®-Mini Shrink Device 2.0 is a lean heat-shrink system with infrared heating elements designed to process heat-shrink tubes onto ultrasonically welded- and crimped splice joints.

 Infrared



Features and Benefits

- Three robust and durable IR ceramic heating elements covering 270° circumference
- Extreme light weight and compact design
- Safe and easy use via Touch Panel
- Calibration period monitoring to ensure process safety
- Acoustic signal for process end and alarm to avoid shrink time exceeding
- Automatic switch-off if the product is not removed to ensure handler safety
- Process launch indication by capacitive sensor
- Ideal heat distribution through special shrink chamber
- Up to 100 data sets storable
- Cost efficient device due to lean feature scope
- Upload of parameters via USB or manually via touch panel
- Compressed air not required
- Adjustable parameters: Shrink time, temperature control
- Password protected programming mode
- Selection of system language: English, German, Mandarin (others on demand)
- Optional wire coil holder on the side of the machine for easier handling
- CE and RoHs conformity

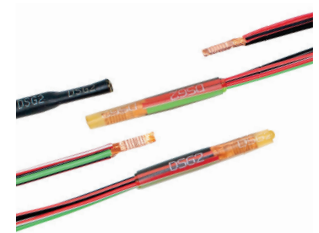
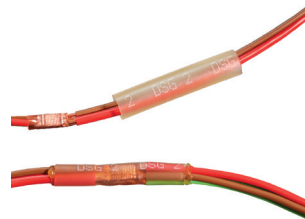
**270° surrounding
IR ceramic heating
elements**

**Highly cost efficient
IR shrink appliance**

Applications

Parallel splices, endsplices

Application samples:



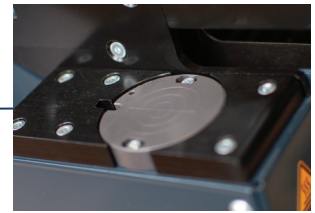
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Operation

The DERAY®-Mini Shrink Device 2.0 has a closed chamber to ensure operator safety and a visible shrink chamber to monitor the application during the shrink process. After introducing the application into the shrink chamber and placing the wires on the capacitive sensors, the set cycle time is shown on the programmable touch panel and the shrink process starts. Once the process is finished an acoustic signal is indicating to remove the application. If the application is not removed, an alarm will start indicating the timeout.

Technical data

PROPERTY	
Electrical connection	1/N/PE AC 230 V 50-60 Hz
Electrical power consumption	0.8 kW
Rated current	4 A
Electrical fuse protection at the owner	16 A
Degree of protection	IP 20
Shrink temperature at the IR heater	530°C (986°F)
Shrink time	6 - 99 sec. depending on wire cross section
Ambient temperature	10 °C - 45 °C (50 °F - 113 °F)
Sound pressure level	approx. 50 dB(A)
Dimensions and weight	
Shrink equipment	w 330 x h 330 x d 310 mm (w 13 x h 13 x d 12 in) 10 kg (22 lbs)



Capacitive sensor for process launch and cycle count.



Infrared quartz heating elements covering 270° circumference with up to 530°C.

Order information

DERAY®-Mini Shrink Device 2.0

Heat-shrink products & sizes:

DSG-Canusa heat-shrink products:

- DERAY®-SpliceMelt: Sizes 1 to 3, length max. 65 mm
- HFTX: Sizes 1 to 3, length max. 65 mm
- CHPA: Sizes 1 to 3, length max. 65 mm
- DERAY®-UMS Sizes 1 to 3, length max. 65 mm

For other products and sizes contact DSG-Canusa Application Engineering.

Scope of delivery:

- Shrink equipment
- Operating manual: English, German (others on demand)

Accessories:

- Calibration sensor
- Wire coil holder

We advise that customers should separately evaluate the suitability of our products for their particular application. Our responsibilities are only those listed in our Standard Terms and Conditions of Sale for these products. Please ask for the latest version of this data sheet. Subject to modification without prior notice.